

A Voltage Reference Circuit in 130 nm CMOS

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Acc.V 10.0 kV 10.0 12.0 kV 3.7 RETRAIT M5-M M M T M OK

Outline

- Motivation
- Circuit architecture
- Implementation
- Measurements
- Summary

Motivation

- Start to learn how to survive in the analog world with supply around 1 to 1.5 V without using thick oxide devices
- Voltage reference circuits are mandatory in:
 - Biasing circuits
 - Bus drivers
 - ADCs
 - ...
- Explore possibility of implementing analog circuits in 0.13 μm CMOS without enclosed transistors

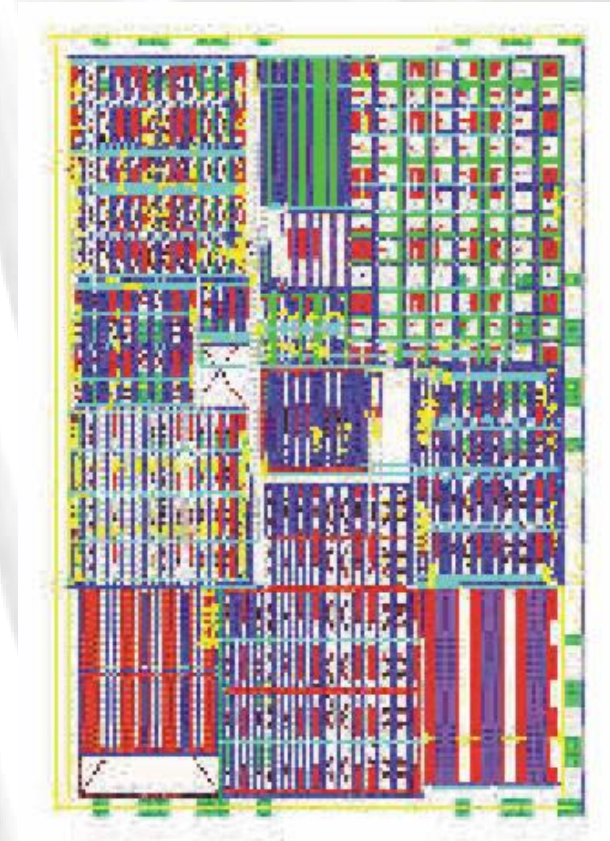
130 nm Technology features

- V_{DD} 1.2 - 1.5 V
- T_{ox} : $\sim 22 \text{ \AA}$
- Types of devices
 - Regular FET, High V_T FET, Low V_T FET, 2.5V IO FET, Zero V_T FET
- Cu metalization
- N-well (dual well option exists)
- Metal width/pitch:
 - M1: 0.16/0.16 μm
 - M2..M5: 0.20/0.20 μm
 - LM: 0.40/0.60 μm

Reference: previous design in 0.25 μm

- Performance summary:
 - $V_{\text{out}} = 1.16 \text{ V @ } 25^\circ \text{C}$
 - $V_{\text{supply_min}} = 1.2 \text{ V}$
 - $\Delta V_{\text{out}} / \Delta V_{\text{supply}} = 1 \text{ mV/V}$
 - $\Delta V_{\text{out}} / \Delta T = -0.22 \text{ mV/}^\circ \text{C}$
 - $P = 62.5 \text{ mW}$
 - Area: $400 \times 275 \mu\text{m}$
 - RH: output drift
 - $0 \text{ mV @ } 1 \text{ Mrad}$
 - $10 \text{ mV @ } 10 \text{ Mrad (first version)}$

Corrected with new
diode layout



Architecture: quick tutorial

Basic Idea:

- 1) Take two voltage sources with different temperature dependence

$$\begin{aligned} V_1 &= V_1(T) & \Delta V_1(T)/\Delta T &= k_1 \cdot T + \dots \\ V_2 &= V_2(T) & \Delta V_2(T)/\Delta T &= k_2 \cdot T + \dots \end{aligned}$$

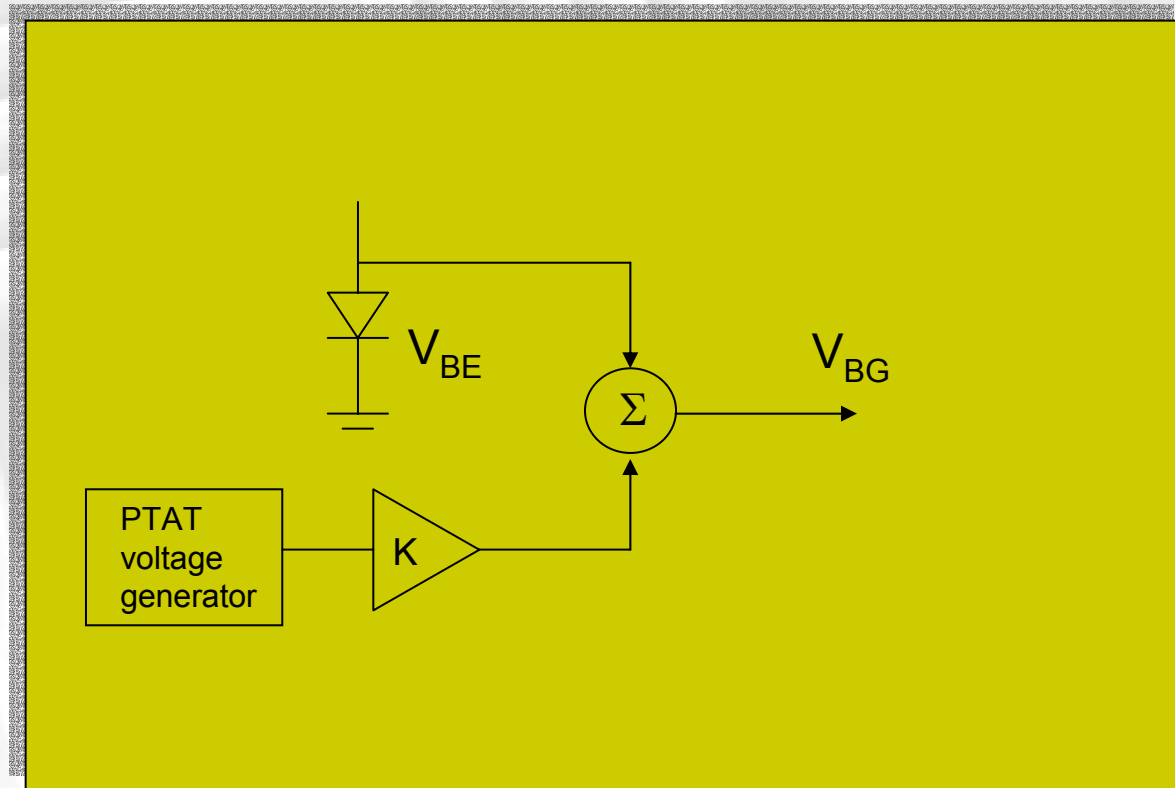
- 2) Combine them in a linear fashion as to obtain $\Delta V/\Delta T = 0$

$$V_{ref} = \alpha \cdot V_1(T) + \beta \cdot V_2(T)$$

choose α and β such as

$$\Delta V_{ref}/\Delta T = 0$$

Architecture: quick tutorial



The PTAT term is produced by biasing two diodes at different current densities

Architecture

$$V_{BG} = V_{BE}(T) + K \cdot V_{PTAT}(T)$$

$$\Delta V_{BE}(T)/\Delta T = \sim -2 \text{ mV/}^\circ\text{C}$$

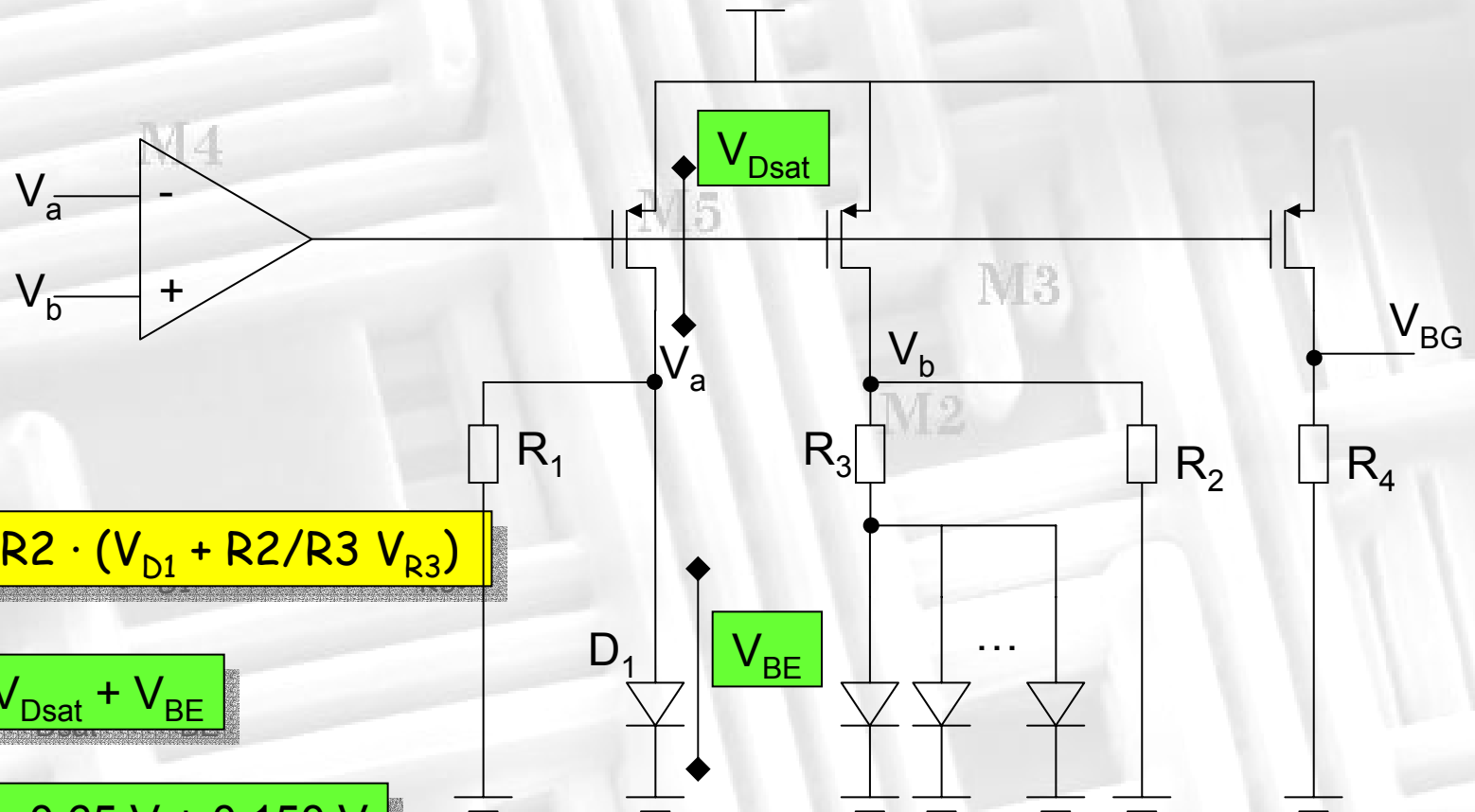
$$\Delta V_{PTAT}(T)/\Delta T = 0.086 \text{ mV/}^\circ\text{C}$$

$$\rightarrow K = \sim 22$$

$$\rightarrow V_{BG} = \sim 1.25 \text{ V}$$

- With V_{DD} @ 1.5 V and below the traditional architecture has to be modified

Low Voltage BG Reference ⁽¹⁾



$$V_{BG} = R_4/R_2 \cdot (V_{D1} + R_2/R_3 V_{R3})$$

$$V_{DDmin} = V_{Dsat} + V_{BE}$$

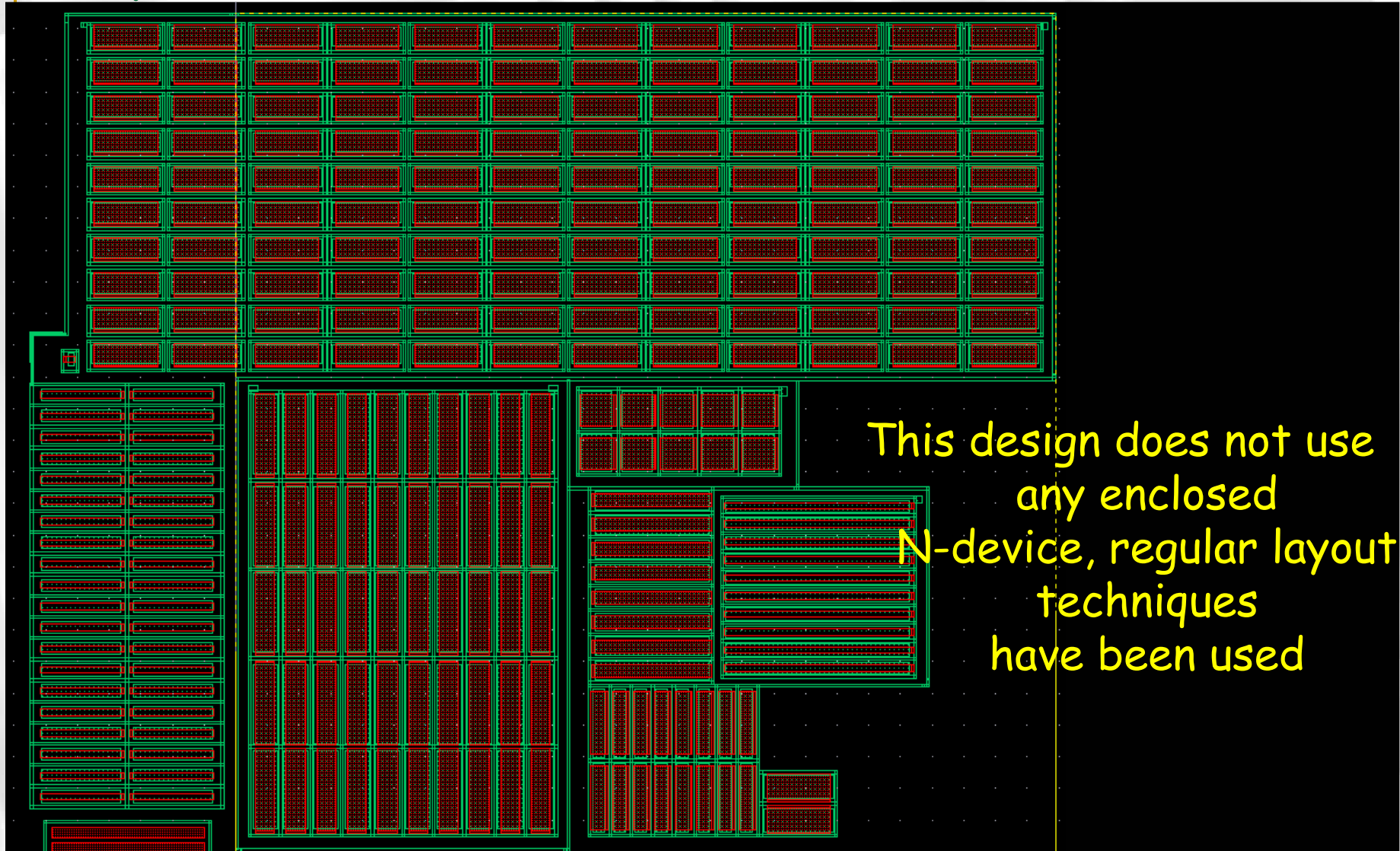
$$V_{DDmin} = \sim 0.65 \text{ V} + 0.150 \text{ V}$$

Low Voltage Bandgap Reference

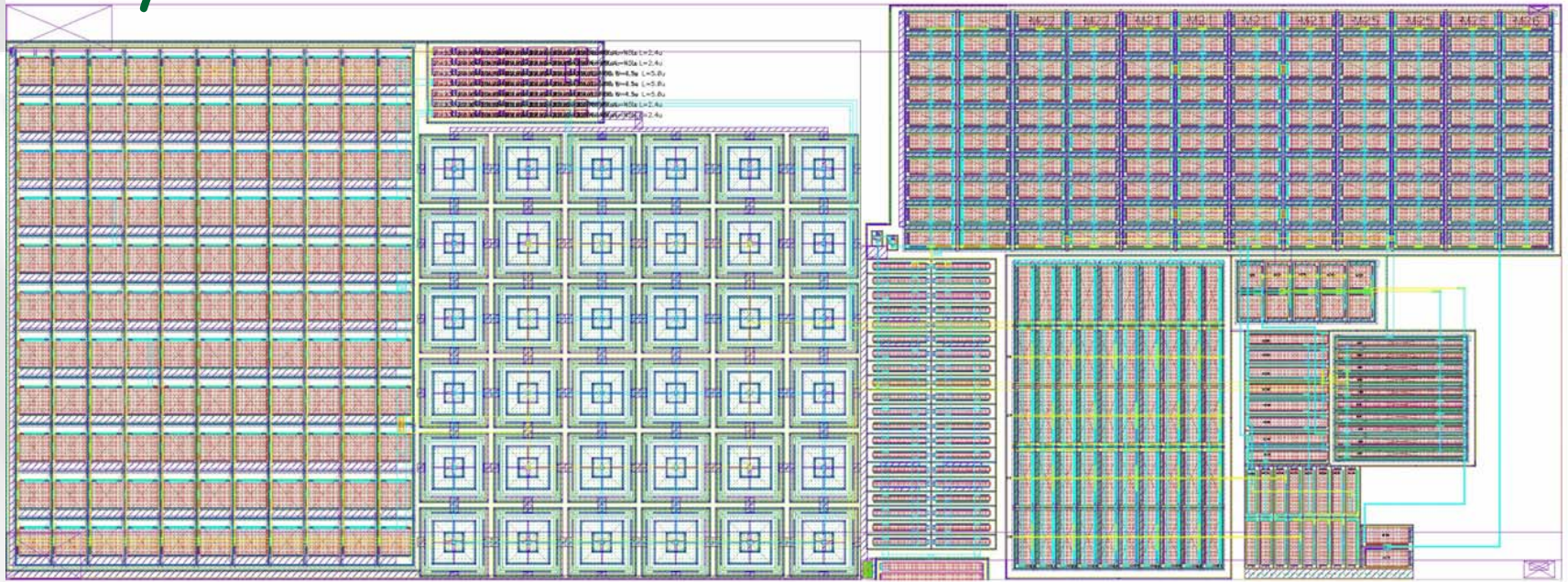
■ Potential problems

- Gain
- Offset of op-amp (measured as 0.5 mV)
- Output range of op-amp
- Second order effects in temperature dependence

Implementation (OP-amp, only poly and RX shown)






Layout in 130 nm



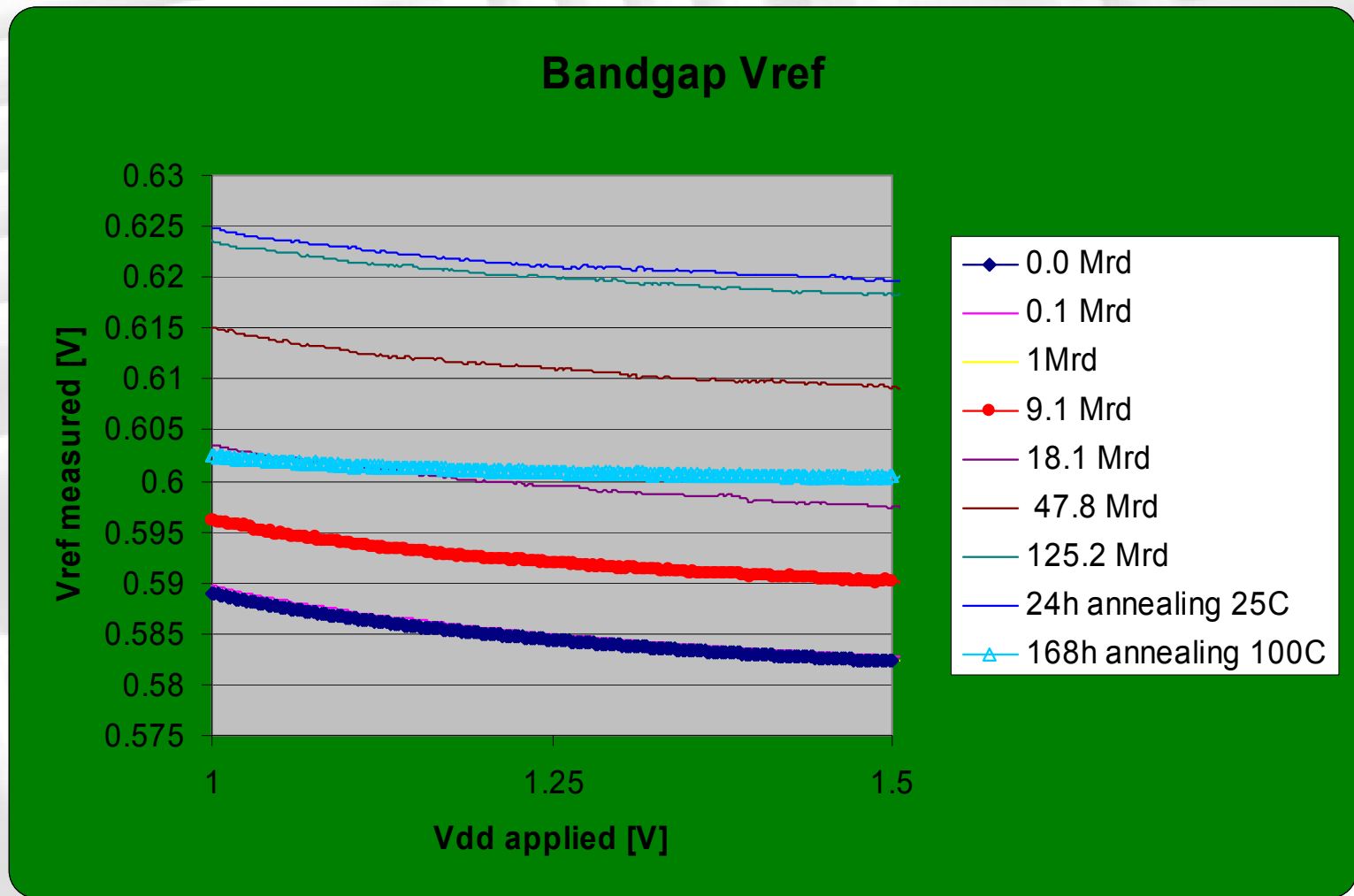
■ Features :

- ❑ $V_{out} = 0.585 \text{ V @ } 25^\circ \text{C}$
- ❑ $V_{supply_min} = 1.0 \text{ V}$
- ❑ Area: $360 \times 130 \text{ } \mu\text{m}$
- ❑ Supply: $\sim 300 \text{ } \mu\text{A}$

Simulation and Measurement Summary

	M4 Simulation forecast (first models)	M5 Measured chip	M3 Re-simulation forecast (new models)
V _{Out}	0.589 V	0.587 V 	0.589
$\Delta V_{\text{out}}/\Delta V_{\text{supply}}$	-0.49 mV/V	14 mV/V 	12 mV/V
$\Delta V_{\text{out}}/\Delta T$	0.014 mV/°C	0.22 mV/°C 	0.075 mV/°C

Irradiation of 130 nm sample (1)



Irradiation Results (2)

- Supply current:

- Pre-irradiation:

$$I_{DD} = 310 \mu A @ 1.5 V^{(1)}$$

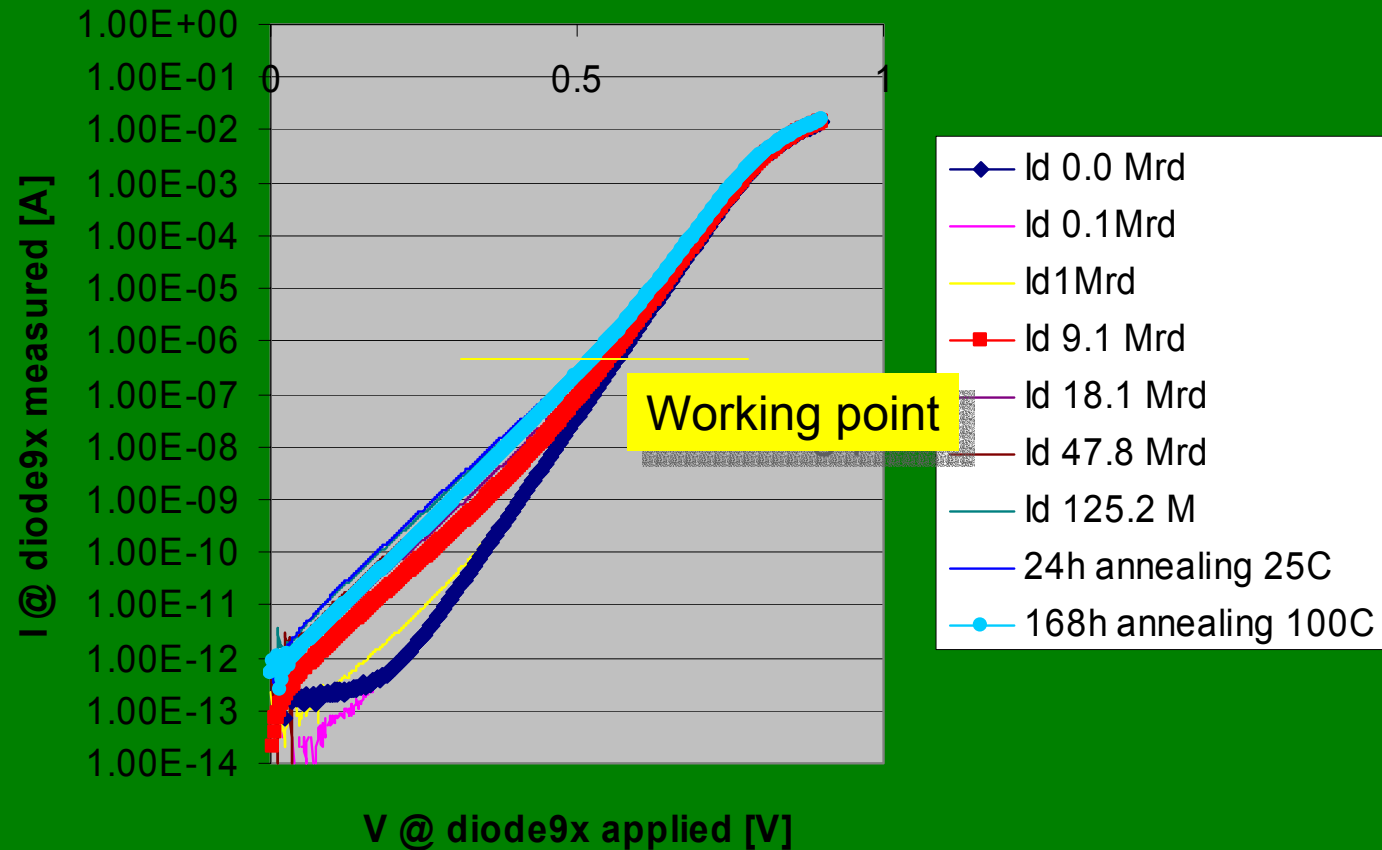
- After 120 Mrad + standard annealing:

$$I_{DD} = 290 \mu A \text{ (but different device)}$$

(1) Measurement actually includes 1 full BG cell + extra test-op-amp

Irradiated Diodes behavior

Diode9x - Irradiation Behavior - log scale

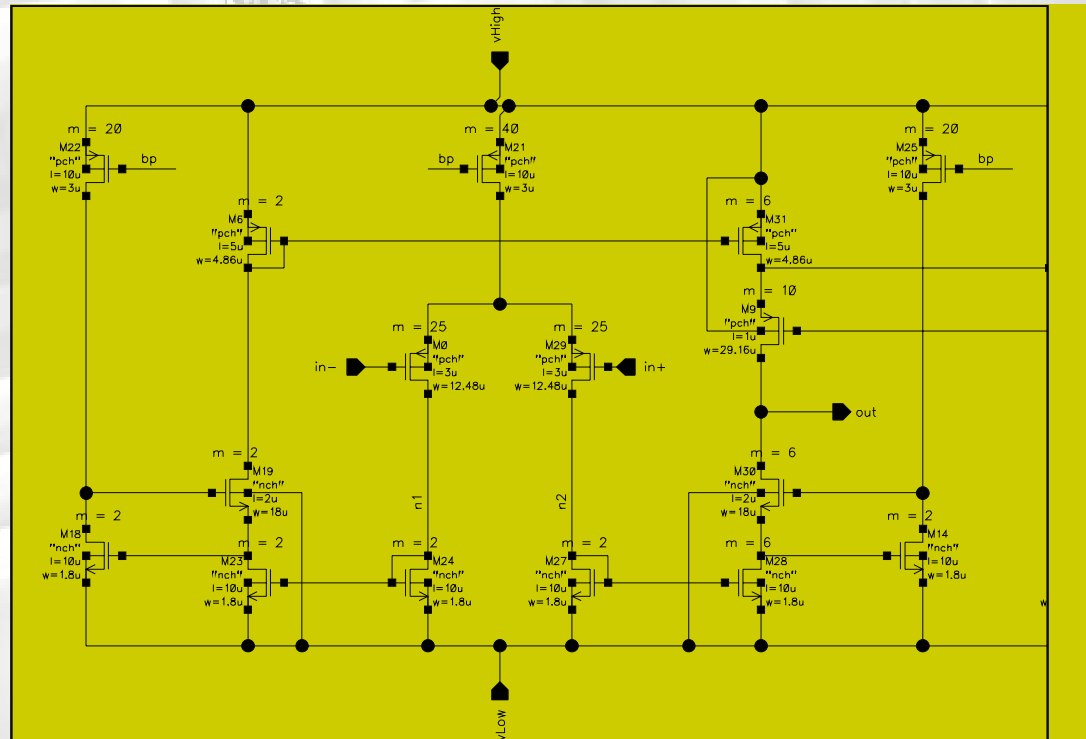


Explanation of voltage drift

- Leakage current in simple diode layout is affected by charge trapped in field oxide above diode
(hypothesis was verified in $\frac{1}{4}$ micron test circuit)
 - Solutions:
 - Increase diode current (to reduce ratio $I_{\text{leakage}}/I_{\text{useful}}$)
 - Modify diode perimeter/area ratio

OTA results

- Two stages, double cascoded configuration with PMOS input devices
- Supply current $\sim 20 \mu\text{A}$
- Output range:
 $1 \text{ V} @ V_{\text{DD}}$ of 1.5 V
- Offset voltage not affected by radiation



Conclusions

- First sub-1 V reference cell with configurable output voltage implemented in 130 nm CMOS
- Functionality OK, but performance degraded due to imprecise process parameters
- Extremely good radiation resistance after 120 Mrad even without enclosed N-channel devices
- New version to be submitted in MPW run at the end of '03